

Research and Progress of High Strength Low Temperature Solders

(Fitech FL170/FL180/FL200)

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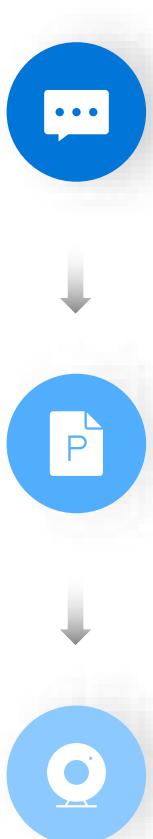
To solve low-temperature solder strength problems /To partially replace high-temperature secondary reflow

The background is a dark blue color with a subtle, abstract pattern. It features several concentric, slightly irregular circles that create a sense of depth and motion. Interspersed among these circles are organic, wavy lines that resemble stylized leaves or ripples on water, adding to the dynamic feel of the design.

01

Objective Review

01- Low-Temperature Solder Market Demand



Anti-Warping Requirements

The development of light, thin, soft and small electronic devices and the market demand for thin substrates and non-temperature-resistant devices require high reliable solder products. SAC solder may lead to many problems like warpage. To handle these problems, low-temperature solder is produced.

Secondary Reflow Process Requirements

At present, the development of high-temperature lead-free solder has reached bottleneck. Since the secondary reflow easily leads to unexpected solder melting, the market needs a solder with a suitable melting temperature for second package process.

Environmental Demand

The global environment and resources are challenged: Solder development has shifted from the leaded to the lead-free era. Tin consumption has risen by more than 40%, and packaging temperatures have increased by 40°C.